



Material Content Data Sheet



Sales Product Name	IPD079N06L3 G			Issued		29. August 2013		
MA#	MA000471074							
Package	PG-TO252-3-311			Weight*		314.03 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.120	0.68	0.68	6751	6751
leadframe	non noble metal	iron	7439-89-6	0.162	0.05		517	
	inorganic material	phosphorus	7723-14-0	0.049	0.02		155	
	non noble metal	copper	7440-50-8	162.275	51.68	51.75	516757	517429
wire	non noble metal	aluminium	7429-90-5	2.179	0.69	0.69	6938	6938
encapsulation	inorganic material	antimonytrioxide	1309-64-4	1.977	0.63		6297	
	plastics	brominated resin	-	2.119	0.67		6747	
	organic material	carbon black	1333-86-4	2.260	0.72		7196	
	plastics	epoxy resin	-	19.068	6.07		60719	
	inorganic material	silicondioxide	60676-86-0	115.818	36.88	44.97	368814	449773
leadfinish	non noble metal	tin	7440-31-5	3.740	1.19	1.19	11910	11910
plating	non noble metal	nickel	7440-02-0	0.086	0.03		275	
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.03	1	276
solder	noble metal	silver	7440-22-4	0.054	0.02		173	
	non noble metal	tin	7440-31-5	0.043	0.01		138	
	non noble metal	lead	7439-92-1	2.076	0.66	0.69	6612	6923
*deviation	< 10%	Sum in total:			100,00			1000000

Important Remarks:

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